



## Material Content Data Sheet



Sales Product Name	ICE3BR0665JZ			Issued		1. August 2018		
MA#	MA000979860							
Package	PG-DIP-7-4			Weight*		653.13 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.709	0.87	0.87	8741	8741
leadframe	inorganic material	phosphorus	7723-14-0	0.049	0.01		74	
	non noble metal	zinc	7440-66-6	0.194	0.03		297	
	non noble metal	iron	7439-89-6	3.884	0.59		5948	
	non noble metal	copper	7440-50-8	157.726	24.15	24.78	241493	247812
wire	noble metal	gold	7440-57-5	0.283	0.04	0.04	434	434
encapsulation	organic material	carbon black	1333-86-4	1.424	0.22		2180	
	plastics	epoxy resin	-	46.044	7.05		70497	
	inorganic material	silicondioxide	60676-86-0	427.211	65.42	72.69	654102	726779
leadfinish	non noble metal	tin	7440-31-5	6.460	0.99	0.99	9890	9890
plating	noble metal	silver	7440-22-4	1.911	0.29	0.29	2926	2926
glue	plastics	epoxy resin	-	0.335	0.05		513	
	noble metal	silver	7440-22-4	1.898	0.29	0.34	2905	3418
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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